5 V Differential PECL to TTL Translator

Description

The MC10ELT/100ELT21 is a differential PECL to TTL translator. Because PECL (Positive ECL) levels are used, only +5 V and ground are required. The small outline 8-lead package and the single gate of the ELT21 makes it ideal for those applications where space, performance and low power are at a premium.

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a $0.01~\mu F$ capacitor and limit current sourcing or sinking to 0.5~mA. When not used, V_{BB} should be left open.

The 100 Series contains temperature compensation.

Features

- 3.5 ns Typical Propagation Delay
- 24 mA TTL Output
- Flow Through Pinouts
- Operating Range: $V_{CC} = 4.75 \text{ V}$ to 5.25 V with GND = 0 V
- Q Output Will Default LOW with Inputs Left Open or < 1.3 V
- Pb-Free Packages are Available



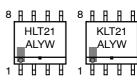
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MARKING DIAGRAMS*



SOIC-8 D SUFFIX CASE 751





TSSOP-8 DT SUFFIX CASE 948R











DFN8 MN SUFFIX CASE 506AA

1

H = MC10 A = Assembly Location
K = MC100 L = Wafer Lot
5C = MC10 Y = Year
2Q = MC100 W = Work Week
M = Date Code ■ = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

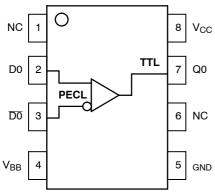


Figure 1. 8-Lead Pinout and Logic Diagram (Top View)

Table 1. PIN DESCRIPTION

| Pin | Function |
|-------------------|-----------------------------------------------------------------------------------------------------------------------------------------|
| Q0 | TTL Outputs |
| D0, DO | PECL Differential Outputs |
| V _{BB} | Reference Voltage Output |
| V _{CC} | Positive Supply |
| GND | Ground |
| NC | No Connect |
| EP | Exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply or leave floating open. |

Table 2. ATTRIBUTES

| Charact | Value | | | | |
|--------------------------------------------------------|----------------------------------|-------------------------------|-------------------------------|--|--|
| Internal Input Pulldown Resisto | Internal Input Pulldown Resistor | | | | |
| Internal Input Pullup Resistor | | N/A | | | |
| ESD Protection | > 2 | ł kV | | | |
| Moisture Sensitivity, Indefinite | Fime Out of Drypack (Note 1) | Pb Pkg | Pb-Free Pkg | | |
| | SOIC-8 TSSOP-8 DFN8 | Level 1 Level 1 Level 1 | Level 1 Level 3 Level 1 | | |
| Flammability Rating | Oxygen Index: 28 to 34 | UL 94 V-0 | @ 0.125 in | | |
| Transistor Count | | 81 De | evices | | |
| Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test | | | | | |

^{1.} For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

| Symbol | Parameter | Condition 1 | Condition 2 | Rating | Unit |
|-------------------|------------------------------------------|--------------------------------------------|--------------------|-------------|--------------|
| V _{CC} | PECL Power Supply | GND = 0 V | | 7 | V |
| V _{IN} | PECL Input Voltage | GND = 0 V | $V_I \leq V_{CC}$ | 0 to 6 | V |
| I _{BB} | V _{BB} Sink/Source | | | ± 0.5 | mA |
| TA | Operating Temperature Range | | | -40 to +85 | °C |
| T _{stg} | Storage Temperature Range | | | -65 to +150 | °C |
| θ_{JA} | Thermal Resistance (Junction-to-Ambient) | 0 lfpm 500 lfpm | SOIC-8 SOIC-8 | 190 130 | °C/W °C/W |
| $\theta_{\sf JC}$ | Thermal Resistance (Junction-to-Case) | Standard Board | SOIC-8 | 41 to 44 | °C/W |
| θ_{JA} | Thermal Resistance (Junction-to-Ambient) | 0 lfpm 500 lfpm | TSSOP-8 TSSOP-8 | 185 140 | °C/W °C/W |
| θJΑ | Thermal Resistance (Junction-to-Ambient) | 0 lfpm 500 lfpm | DFN8 DFN8 | 129 84 | °C/W °C/W |
| T _{sol} | Wave Solder Pb Pb-Free | <2 to 3 sec @ 248°C <2 to 3 sec @ 260°C | | 265 265 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 4. 10ELT SERIES PECL INPUT DC CHARACTERISTICS V_{CC} = 5.0 V; GND = 0.0 V (Note 2)

| | | | -40°C | | | 25°C | | | 85°C | | |
|--------------------|----------------------------------------------------------------------------|------|-------|------|------|------|------|------|------|------|------|
| Symbol | Characteristic | Min | Тур | Max | Min | Тур | Max | Min | Тур | Max | Unit |
| V _{IH} | Input HIGH Voltage (Single-Ended) | 3770 | | 4110 | 3870 | | 4190 | 3930 | | 4265 | mV |
| V _{IL} | Input LOW Voltage (Single-Ended) | 3050 | | 3500 | 3050 | | 3520 | 3050 | | 3555 | mV |
| V _{BB} | Output Voltage Reference | 3.57 | | 3.7 | 3.65 | | 3.75 | 3.69 | | 3.81 | V |
| V _{IHCMR} | Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3) | 2.2 | | 5.0 | 2.2 | | 5.0 | 2.2 | | 5.0 | V |
| I _{IH} | Input HIGH Current | | | 255 | | | 175 | | | 175 | μΑ |
| I _{IL} | Input LOW Current | 0.5 | | | 0.5 | | | 0.3 | | | μΑ |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 2. Output parameters vary 1:1 with V_{CC} . V_{CC} can vary \pm 0.25 V.
- 3. V_{IHCMR} min varies 1:1 with GND, V_{IHCMR} max varies 1:1 with V_{CC} .

Table 5. 100ELT SERIES PECL INPUT DC CHARACTERISTICS V_{CC} = 5.0 V; GND = 0.0 V (Note 4)

| | | | -40°C | | | 25°C | | | 85°C | | |
|--------------------|-------------------------------------------------------------------------------|------|-------|------|------|------|------|------|------|-------|------|
| Symbol | Characteristic | Min | Тур | Max | Min | Тур | Max | Min | Тур | Max | Unit |
| V _{IH} | Input HIGH Voltage (Single-Ended) | 3835 | | 4120 | 3835 | | 4120 | 3835 | | 4120 | mV |
| V _{IL} | Input LOW Voltage (Single-Ended) | 3190 | | 3525 | 3190 | | 3525 | 3190 | | 3525 | mV |
| V _{BB} | Output Voltage Reference | 3.62 | | 3.74 | 3.62 | | 3.74 | 3.62 | | 3.745 | V |
| V _{IHCMR} | Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 5) | 2.2 | | 5.0 | 2.2 | | 5.0 | 2.2 | | 5.0 | V |
| I _{IH} | Input HIGH Current | | | 255 | | | 175 | | | 175 | μΑ |
| I _{IL} | Input LOW Current | 0.5 | | | 0.5 | | | 0.5 | | | μΑ |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket o printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 4. Input parameters vary 1:1 with V_{CC} . V_{CC} can vary \pm 0.25 V.
- 5. V_{IHCMR} min varies 1:1 with GND, V_{IHCMR} max varies 1:1 with V_{CC}.

Table 6. TTL OUTPUT DC CHARACTERISTICS V_{CC} = 4.75 V to 5.25 V; T_A = -40°C to 85°C)

| Symbol | Characteristic | Condition | Min | Тур | Max | Unit |
|------------------|------------------------------|---------------------------|------|-----|----------|------|
| V _{OH} | Output HIGH Voltage | I _{OH} = -3.0 mA | 2.4 | | (Note 6) | V |
| V _{OL} | Output LOW Voltage | I _{OL} = 24 mA | | | 0.5 | V |
| I _{CCH} | Power Supply Current | | | 20 | 29 | mA |
| I _{CCL} | Power Supply Current | | | 22 | 32 | mA |
| Ios | Output Short Circuit Current | | -150 | | -60 | mA |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

6. Maximum level is V_{CC} – 0.7 by design.

AC CHARACTERISTICS $V_{CC} = 4.75 \text{ V}$ to 5.25 V; GND = 0.0 V (Note 7)

| | | −40°C | | 25°C | | | 85°C | | | | |
|--------------------------------|-----------------------------------|-------|-----|------|-----|-----|------|-----|-----|------|------|
| Symbol | Characteristic | Min | Тур | Max | Min | Тур | Max | Min | Тур | Max | Unit |
| f _{max} | Maximum Toggle Frequency | | | | | 100 | | | | | MHz |
| t _{JITTER} | Random Clock Jitter (RMS) | | | | | 35 | | | | | ps |
| t _{PLH} | Propagation Delay @ 1.5 V | 2.0 | | 5.5 | 2.0 | | 5.5 | 2.0 | | 5.5 | ns |
| t _{PHL} | Propagation Delay @ 1.5 V | 2.0 | | 5.5 | 2.0 | | 5.5 | 2.0 | | 5.5 | ns |
| V_{PP} | Input Swing (Note 8) | 200 | | 1000 | 200 | | 1000 | 200 | | 1000 | mV |
| t _r /t _f | Output Rise/Fall Time (10-90%) | | | | | 750 | | | | | ps |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 7. R_L = 500 Ω to GND and C_L = 20 pF to GND. Refer to Figure 2.
- 8. VPP(min) is the minimum input swing for which AC parameters are guaranteed. The device has a DC gain of -[40.

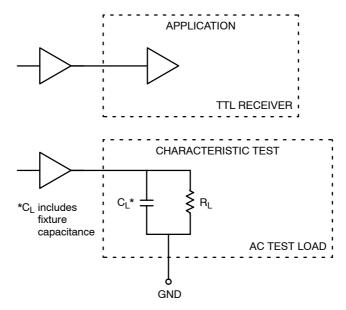


Figure 2. TTL Output Loading Used for Device Evaluation

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|-----------------|----------------------|-----------------------|
| MC10ELT21D | SOIC-8 | 98 Units / Rail |
| MC10ELT21DG | SOIC-8 (Pb-Free) | 98 Units / Rail |
| MC10ELT21DR2 | SOIC-8 | 2500 / Tape & Reel |
| MC10ELT21DR2G | SOIC-8 (Pb-Free) | 2500 / Tape & Reel |
| MC10ELT21DT | TSSOP-8 | 100 Units / Rail |
| MC10ELT21DTG | TSSOP-8 (Pb-Free) | 100 Units / Rail |
| MC10ELT21DTR2 | TSSOP-8 | 2500 / Tape & Reel |
| MC10ELT21DTR2G | TSSOP-8 (Pb-Free) | 2500 / Tape & Reel |
| MC10ELT21MNR4 | DFN8 | 1000 / Tape & Reel |
| MC10ELT21MNR4G | DFN8 (Pb-Free) | 1000 / Tape & Reel |
| MC100ELT21D | SOIC-8 | 98 Units / Rail |
| MC100ELT21DG | SOIC-8 (Pb-Free) | 98 Units / Rail |
| MC100ELT21DR2 | SOIC-8 | 2500 / Tape & Reel |
| MC100ELT21DR2G | SOIC-8 (Pb-Free) | 2500 / Tape & Reel |
| MC100ELT21DT | TSSOP-8 | 100 Units / Rail |
| MC100ELT21DTG | TSSOP-8 (Pb-Free) | 100 Units / Rail |
| MC100ELT21DTR2 | TSSOP-8 | 2500 / Tape & Reel |
| MC100ELT21DTR2G | TSSOP-8 (Pb-Free) | 2500 / Tape & Reel |
| MC100ELT21MNR4 | DFN8 | 1000 / Tape & Reel |
| MC100ELT21MNR4G | DFN8 (Pb-Free) | 1000 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AND8001/D - The ECL Translator Guide
AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

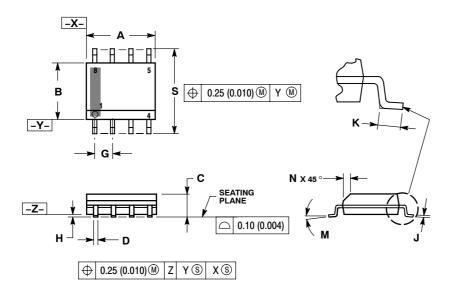
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

SOIC-8 NB CASE 751-07 **ISSUE AH**



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

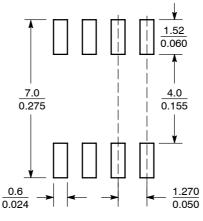
 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.

 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006)
 PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT
 MAXIMUM MATERIAL CONDITION.
 6. 751–01 THRU 751–06 ARE OBSOLETE. NEW
 STANDARD IS 751, 07
- STANDARD IS 751-07.

| | MILLIN | IETERS | INC | HES | | |
|-----|-----------|---------|-----------|-------|--|--|
| DIM | MIN | MAX | MIN | MAX | | |
| Α | 4.80 | 5.00 | 0.189 | 0.197 | | |
| В | 3.80 | 4.00 | 0.150 | 0.157 | | |
| C | 1.35 | 1.75 | 0.053 | 0.069 | | |
| D | 0.33 0.51 | | 0.013 | 0.020 | | |
| G | 1.27 | 7 BSC | 0.050 BSC | | | |
| Н | 0.10 | 0.25 | 0.004 | 0.010 | | |
| J | 0.19 | 0.25 | 0.007 | 0.010 | | |
| K | 0.40 1.27 | | 0.016 | 0.050 | | |
| М | 0 ° | 0 ° 8 ° | | 8 ° | | |
| N | 0.25 | 0.50 | 0.010 | 0.020 | | |
| S | 5.80 | 6.20 | 0.228 | 0.244 | | |

SOLDERING FOOTPRINT*

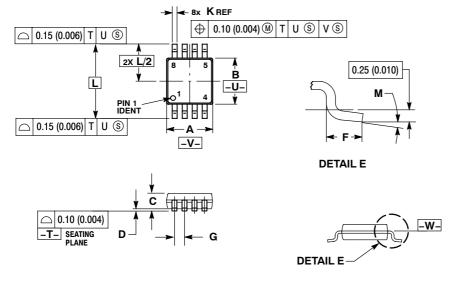


 $\left(\frac{\text{mm}}{\text{inches}}\right)$ SCALE 6:1

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-8 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.
- 2. CONTINGUING DIMENSION. MILLIDIETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH.
 PROTRUSIONS OR GATE BURRS. MOLD FLASH
 OR GATE BURRS SHALL NOT EXCEED 0.15
- (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 5. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
 6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| | MILLIN | IETERS | INCHES | | | |
|-----|--------|--------|--------|-------|--|--|
| DIM | MIN | MAX | MIN | MAX | | |
| Α | 2.90 | 3.10 | 0.114 | 0.122 | | |
| В | 2.90 | 3.10 | 0.114 | 0.122 | | |
| C | 0.80 | 1.10 | 0.031 | 0.043 | | |
| D | 0.05 | 0.15 | 0.002 | 0.006 | | |
| F | 0.40 | 0.70 | 0.016 | 0.028 | | |
| G | 0.65 | BSC | 0.026 | BSC | | |
| K | 0.25 | 0.40 | 0.010 | 0.016 | | |
| L | 4.90 | BSC | 0.193 | BSC | | |
| М | ٥° | 6 ° | 0° | 6° | | |

PACKAGE DIMENSIONS

DFN8 CASE 506AA-01 ISSUE D

NOTES:

DIM

A1 Аз

D

D2

DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 .

CONTROLLING DIMENSION: MILLIMETERS.
DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL. COPLANARITY APPLIES TO THE EXPOSED

PAD AS WELL AS THE TERMINALS. MILLIMETERS

> 1.00 0.00 0.05

MIN MAX

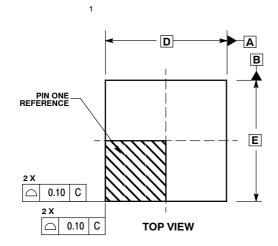
0.20 REF 0.20 0.30 2.00 BSC

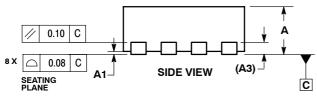
1.10 1.30 2.00 BSC 0.70 0.90

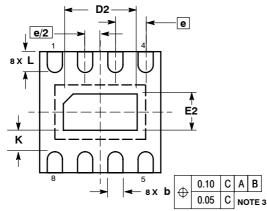
0.50 BSC

0.20 0.25 0.35

0.80







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